



**PROJECT INITIATION  
NOTIFICATION SYSTEM FORM**

Project Registration Date (dd-mmm-yyyy) completed by EIA:	<b>19MAY06</b>
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**Electronic Industries Alliance PINS: (01OCT2004)**

1. Project Number Assigned by EIA:	<b>PN-5141</b>		
2. Final Published Document Number Assigned:	<b>J-STD-002C</b>		
3. Title of Final Published Document:	<b>Solderability Tests for Component Leads, Terminations, Lugs, Terminals and Wires</b>		
4. Project Intent: (Check the applicable box(s) below)			
Create a New Document		Modify Existing Document	
EIA Component Bulletin	<input type="checkbox"/>	Revise current published document	<input checked="" type="checkbox"/>
EIA standard	<input type="checkbox"/>	Revise and Redesignate current published document	<input type="checkbox"/>
Joint Industry Document	<input type="checkbox"/>	Revise, Redesignate and Consolidate current document	<input type="checkbox"/>
Create new American National Standard (ANSI)	<input type="checkbox"/>	Revise and Partition current document	<input type="checkbox"/>
Conduct Survey	<input type="checkbox"/>	Reaffirm current document	<input type="checkbox"/>
Other (Please explain↓)	<input type="checkbox"/>	Reaffirm and Redesignate current document	<input type="checkbox"/>
		Supplement to a current document	<input type="checkbox"/>
		Withdraw current document	<input type="checkbox"/>
5. Estimated Project Completion Date (mmm yy):↓	Convert to Historical Document designation		<input type="checkbox"/>
SEP06	Other (Please explain↓)		<input type="checkbox"/>

6. Description of Contents of Document: (Provide a one paragraph description, not to exceed 500 characters.)

**This joint standard is being revised to level C. 3 organizations are jointly preparing this revision; EIA/ECA, IPC, and JEDEC. This standard prescribes test methods, defect definitions, acceptance criteria, and illustrations for assessing the solderability of electronic component leads, terminations, solid wires, stranded wires, lugs, and tabs. This standard also includes a test method for the Resistance to Dissolution/Dewetting of Metallization. Solderability testing of components is considered a destructive test and the tested component should not be used for functional electrical evaluation. This standard is intended for use by both vendor and user.**

7. Units of Measurement Used: (check applicable boxes→)  Metric  US  Non-Measurement Sensitive

8. Formulating Body  
(Organization, Committee/Subcommittee Title and Acronym): **EIA/ECA STC with IPC & JEDEC**

9. Designated Formulating Group Project Author/Editor/Leader: (Specify name and complete contact information, address, phone, email, etc. If none is indicated, Default Project Point Contact will be Formulating Group Chair as completed in 9. below.)

Name:	<b>Doug Romm</b>	Phone:	
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10. Formulating Group Chair: (Specify name and complete contact information, address, phone, email, etc.)

Name:	<b>Doug Romm</b>	Phone:	
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